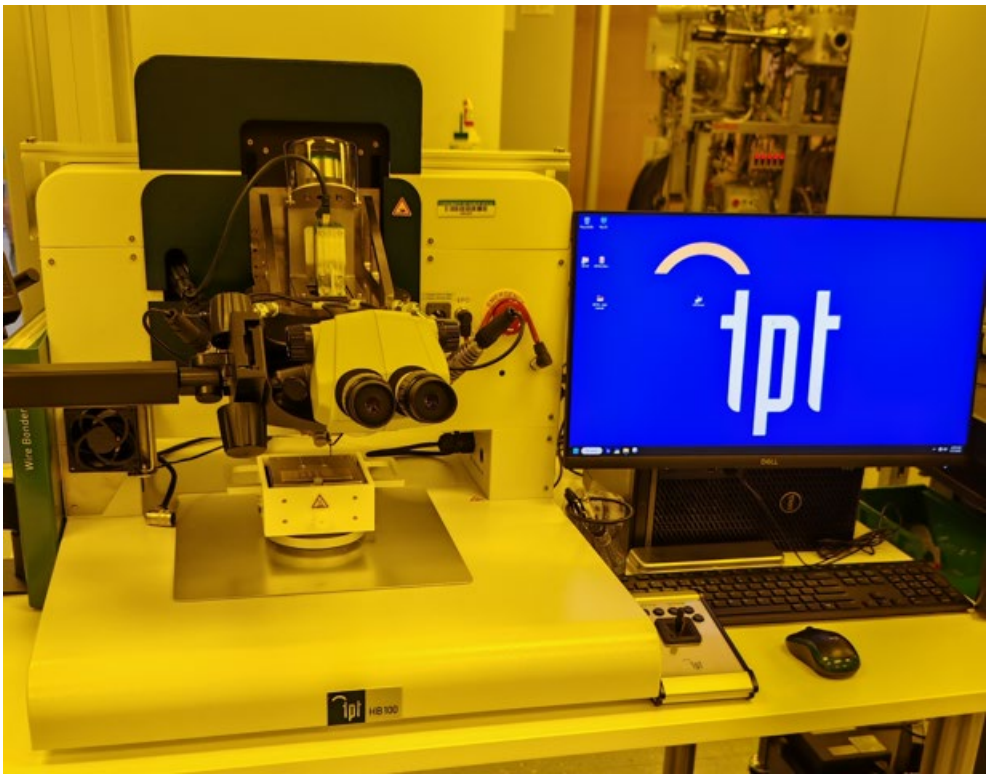
TPT HB100 Wire Bonder

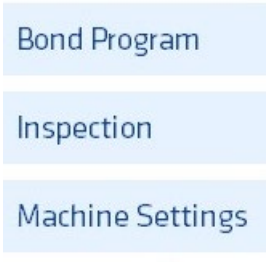
10/26/2026



Operation Steps:

1. Turn on the power switch on the back of the wirebonder main console.
2. Open the software and system initialize:





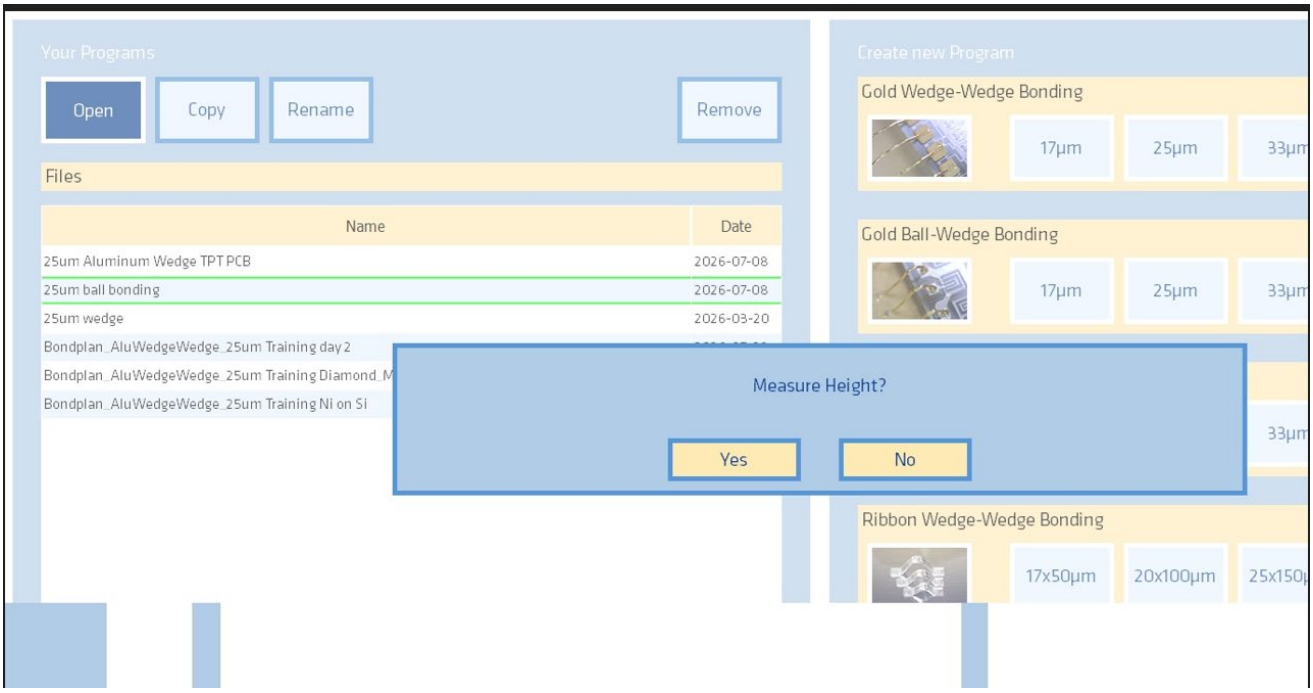
3. Click “Bond Program”

4. Choose the program eg: 1. for wedge bond setup “25um Aluminum TPT PCB” 2. for ball bond setup “25um ball bonding”

   For wedge bonding, unplug the red EFO cable from Bond Head if not unplugged.



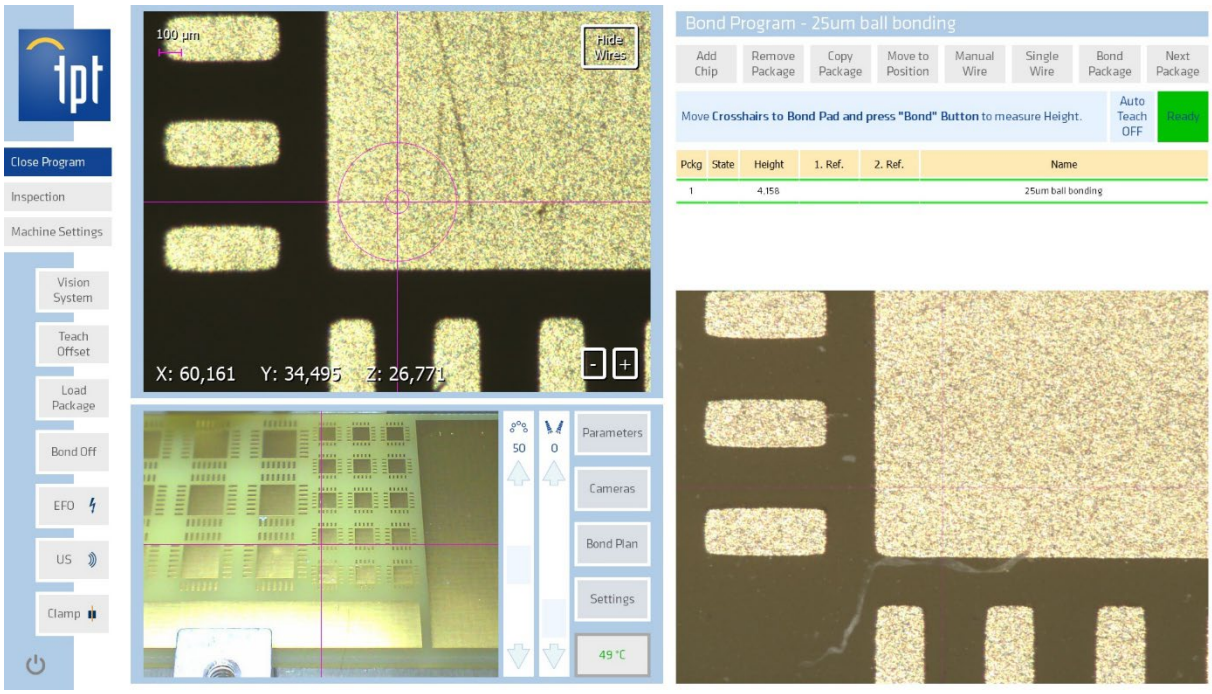
5. Click “Open”. Click “yes” for Measure Height



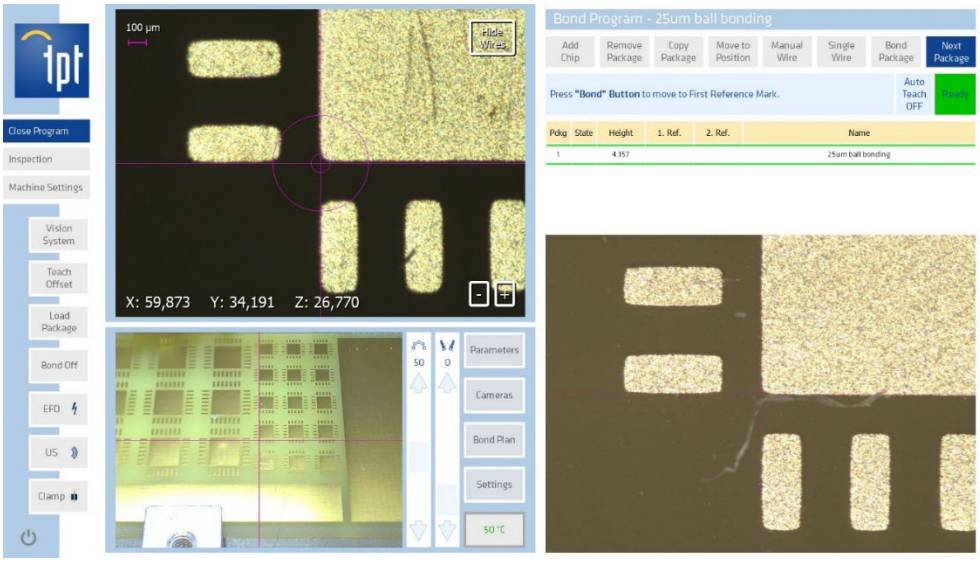
6. Follow the instruction on the upper right line: Press “Bond” button to move to Measure Height Position.



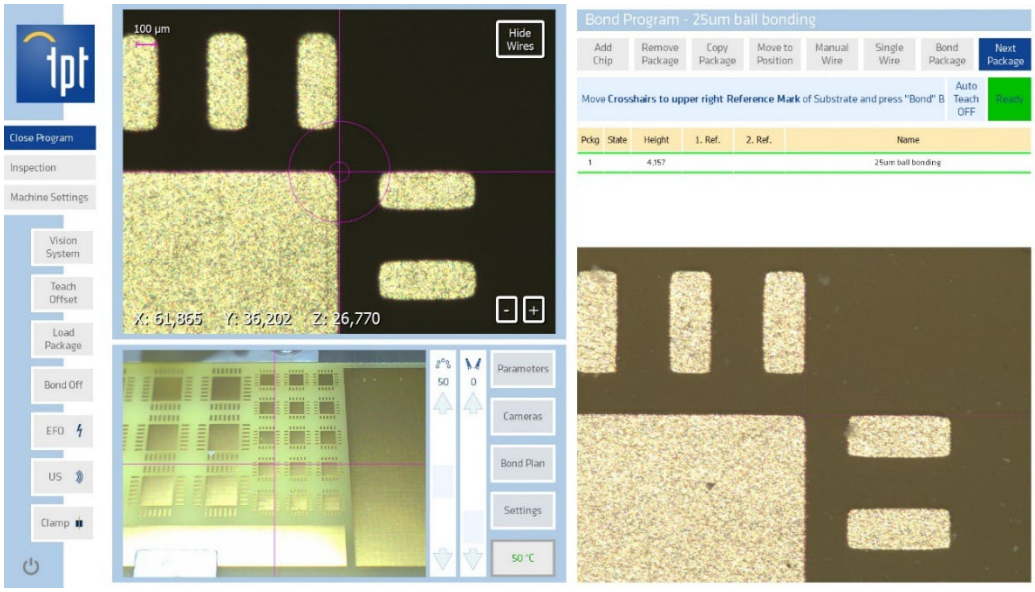
7. Use the joystick to move the lines to the measure height point which is shown in the lower right pic. Then press “Bond” button.



8. Follow instructions for 4 reference marks: use joystick to move the lines to the 1st reference mark as shown in lower right pic.



9. 2nd reference mark: use joystick to move the lines to the 2nd reference mark as shown in lower right pic.

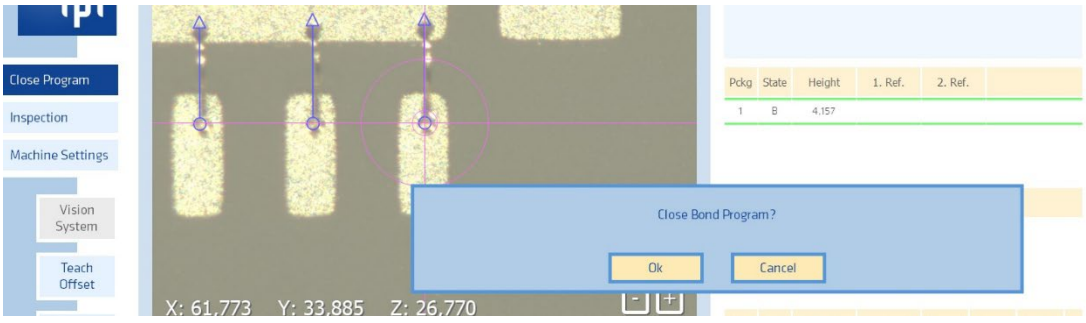


10. Start bonding: choose “continue package”

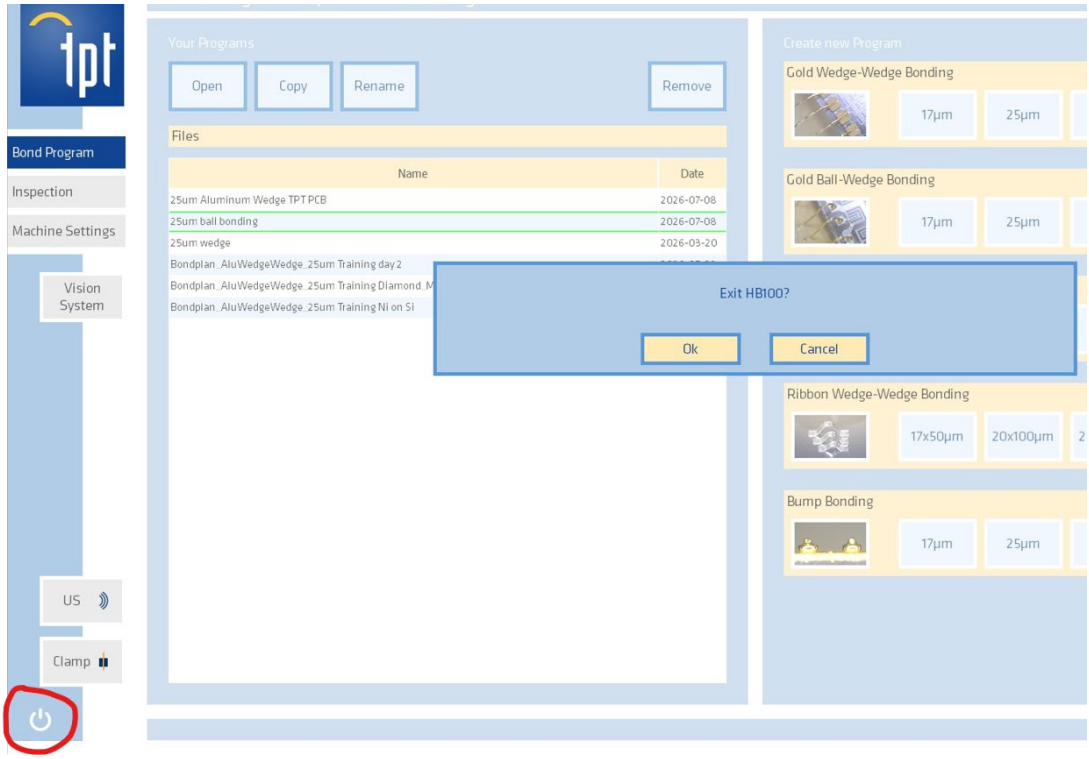


11. All bonds are done and verify them through microscope.

12. Close the program:



13. Exit HB100 and Power off back switch.



For Nonstandard sample (different heights at two bond pad areas):

1. To create a new program for nonstandard sample, Make sure change the wire parameters before doing bonding. The default parameter will cause thread to be broken.

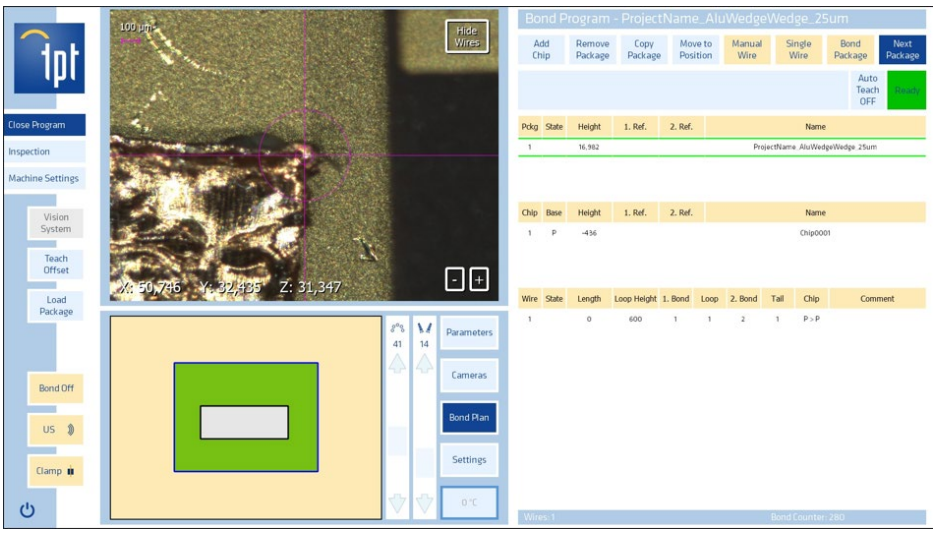
1st bond	2nd bond
80	100
Force	Force
200	200

2. Measure 1st bond pad height at small pad

3. Four corners to define the area along the outer edge

4. Push “STOP” button to exit measure height again step

5. Click on “Package line” Then click “Add Chip” to follow onscreen instruction to add 2nd pad position for heigh measurement.



6. Move 3 spots of the inside square are to define the area of 2nd height.

7. Push “STOP” button to exit the measure height again step.

   Click on the wire line to change the parameters to

1st bond Force	2nd bond Force	
80	100	height to 800
200	200	

8. Click “Manual Wire” to select 1st and 2nd spots for wire bonding.